

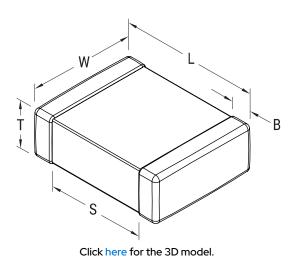
# C0805H180J3GACTU

Aliases (C0805H180J3GAC7800)

**Specifications** 

Insulation Resistance

SMD Indust COG HT200C, Ceramic, 18 pF, 5%, 25 VDC, COG, SMD, MLCC, High Temperature, Ultra-Stable, Low Loss, 0805, 0.7 mm



General Information	
Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Measurement Condition 1 MHz 1.0Vrms  Tolerance 5%  Voltage DC 25 VDC  Dielectric Withstanding Voltage 62.5 VDC  Temperature Range -55/+200°C  Temp. Coefficient COG  Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor 0.1% 1 MHz 1.0Vrms  Aging Rate 0% Loss/Decade Hour	Capacitance	18 pF
Voltage DC  Dielectric Withstanding Voltage  62.5 VDC  Temperature Range  -55/+200°C  Temp. Coefficient  Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor  25 VDC  62.5 VDC  30 VDC  30 PDM/C, 1MegaHz 1.0Vrms	Measurement Condition	1 MHz 1.0Vrms
Dielectric Withstanding Voltage 62.5 VDC  Temperature Range -55/+200°C  Temp. Coefficient COG  Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor 0.1% 1 MHz 1.0Vrms	Tolerance	5%
Temperature Range -55/+200°C  Temp. Coefficient COG  Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor 0.1% 1 MHz 1.0Vrms	Voltage DC	25 VDC
Temp. Coefficient COG  Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor 0.1% 1 MHz 1.0Vrms	Dielectric Withstanding Voltage	62.5 VDC
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor  30 ppm/C, 1MegaHz 1.0Vrms  0.1% 1 MHz 1.0Vrms	Temperature Range	-55/+200°C
Reference to +25°C and 0 VDC Applied (TCC)  Dissipation Factor  0.1% 1 MHz 1.0Vrms	Temp. Coefficient	COG
	Reference to +25°C and 0 VDC	30 ppm/C, 1MegaHz 1.0Vrms
Aging Rate 0% Loss/Decade Hour	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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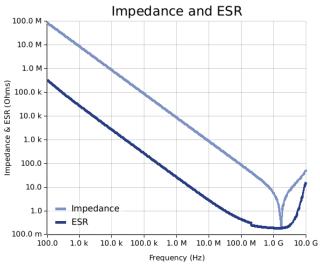


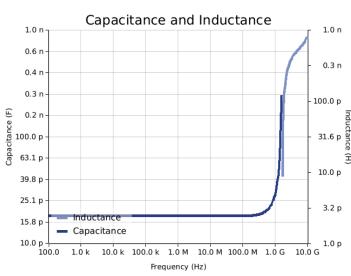
## C0805H180J3GACTU

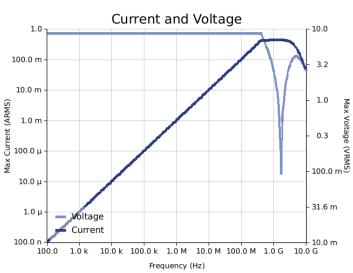
Aliases (C0805H180J3GAC7800) SMD Indust COG HT200C, Ceramic, 18 pF, 5%, 25 VDC, COG, SMD, MLCC, High Temperature, Ultra-Stable, Low Loss, 0805, 0.7 mm

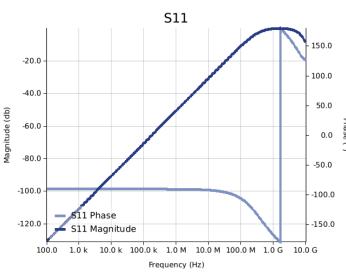
### **Simulations**

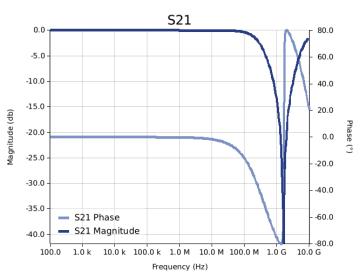
For the complete simulation environment please visit K-SIM.











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### C0805H180J3GACTU

Aliases (C0805H180J3GAC7800) SMD Indust COG HT200C, Ceramic, 18 pF, 5%, 25 VDC, COG, SMD, MLCC, High Temperature, Ultra-Stable, Low Loss, 0805, 0.7 mm

#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question.

  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

  Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.

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